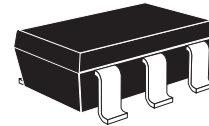


# ZXMN6A08E6

## 60V N-CHANNEL ENHANCEMENT MODE MOSFET

### SUMMARY

$V_{(BR)DSS}$	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
60	0.080 @ $V_{GS} = 10V$	3.5
	0.150 @ $V_{GS} = 4.5V$	2.5



SOT23-6

### DESCRIPTION

This new generation trench MOSFET from Zetex features a unique structure combining the benefits of low on-resistance and fast switching, making it ideal for high efficiency power management applications.

### FEATURES

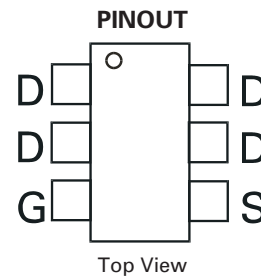
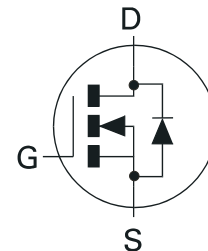
- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- SOT23-6 package

### APPLICATIONS

- DC - DC converters
- Power management functions
- Disconnect switches
- Motor control

### ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMN6A08E6TA	7"	8mm	3000 units
ZXMN6A08E6TC	13"	8mm	10000 units



### DEVICE MARKING

- 6A8

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# ZXMN6A08E6

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DSS}$	60	V
Gate Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current $V_{GS}=10V$ ; $T_A=25^\circ C$ (b) $V_{GS}=10V$ ; $T_A=70^\circ C$ (b) $V_{GS}=10V$ ; $T_A=25^\circ C$ (a)	$I_D$	3.5 2.8 2.8	A
Pulsed Drain Current (c)	$I_{DM}$	16	A
Continuous Source Current (Body Diode) (b)	$I_S$	2.6	A
Pulsed Source Current (Body Diode) (c)	$I_{SM}$	16	A
Power Dissipation at $T_A=25^\circ C$ (a) Linear Derating Factor	$P_D$	1.1 8.8	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (b) Linear Derating Factor	$P_D$	1.7 13.6	W mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j:T_{stg}$	-55 to +150	$^\circ C$

## THERMAL RESISTANCE

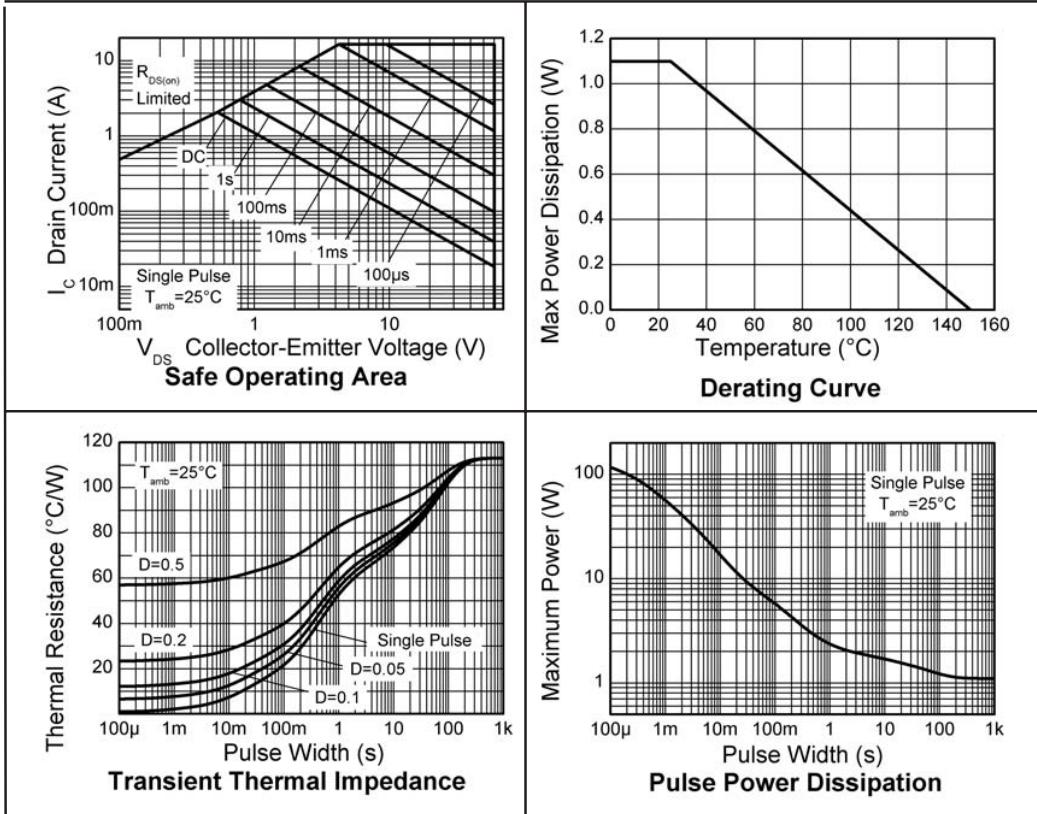
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	113	$^\circ C/W$
Junction to Ambient (b)	$R_{\theta JA}$	73	$^\circ C/W$

### NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions  
(b) For a device surface mounted on FR4 PCB measured at  $t \leq 10$  secs.  
(c) Repetitive rating 25mm x 25mm FR4 PCB,  $D = 0.02$ , pulse width 300 $\mu s$  - pulse width limited by maximum junction temperature.

# ZXMN6A08E6

## CHARACTERISTICS



# ZXMN6A08E6

**ELECTRICAL CHARACTERISTICS** (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

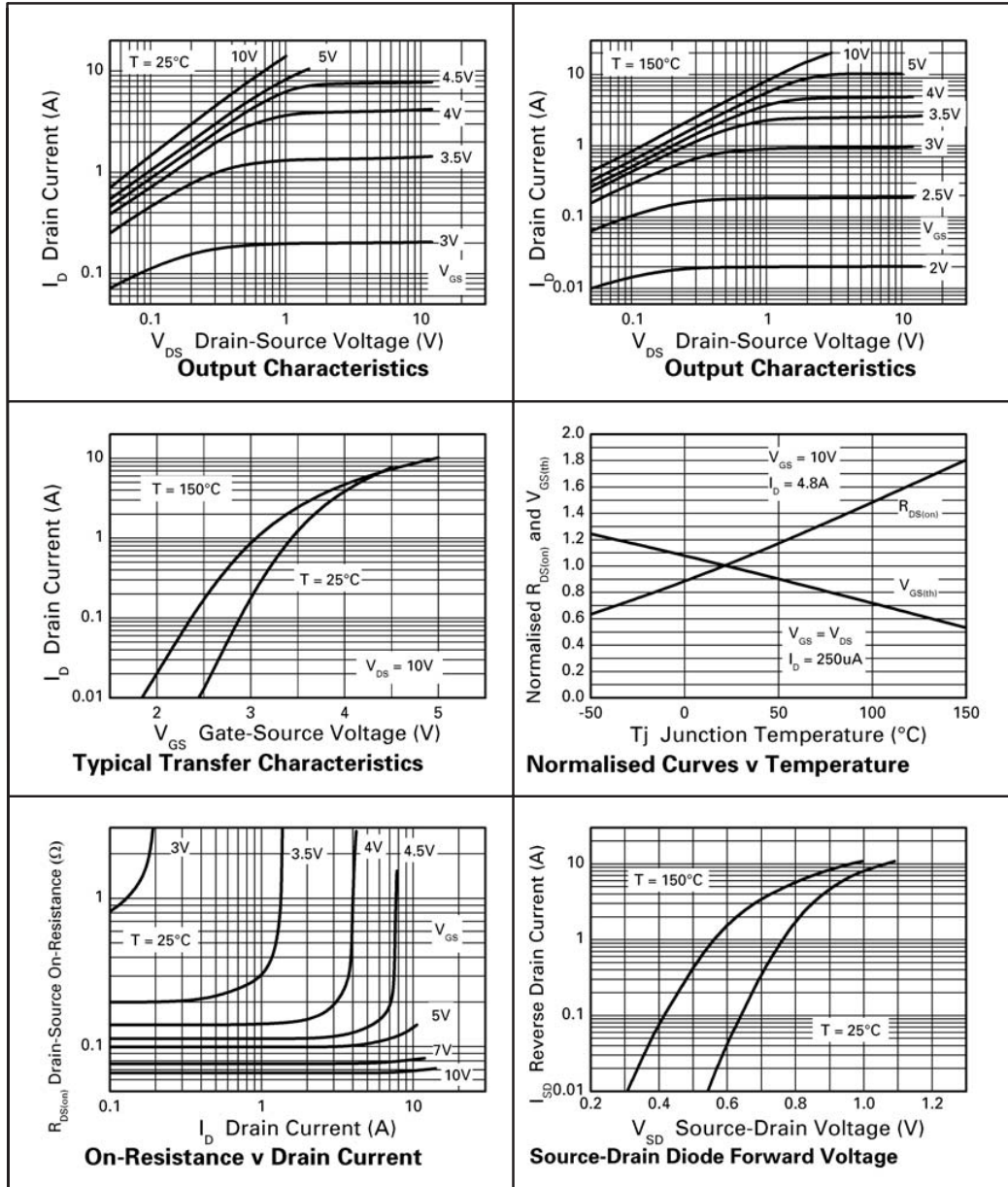
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	60			V	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	$I_{DSS}$			0.5	$\mu\text{A}$	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$
Gate-Body Leakage	$I_{GSS}$			100	nA	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	1			V	$I_D=250\mu\text{A}, V_{DS}=V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.080 0.150	$\Omega$ $\Omega$	$V_{GS}=10\text{V}, I_D=4.8\text{A}$ $V_{GS}=4.5\text{V}, I_D=4.2\text{A}$
Forward Transconductance (1)(3)	$g_{fs}$		6.6		S	$V_{DS}=15\text{V}, I_D=4.8\text{A}$
<b>DYNAMIC (3)</b>						
Input Capacitance	$C_{iss}$		459		pF	$V_{DS}=40\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$
Output Capacitance	$C_{oss}$		44.2		pF	
Reverse Transfer Capacitance	$C_{rss}$		24.1		pF	
<b>SWITCHING(2) (3)</b>						
Turn-On Delay Time	$t_{d(on)}$		2.6		ns	$V_{DD}=30\text{V}, I_D=1.5\text{A}$ $R_{G\equiv 6.0\Omega}, V_{GS}=10\text{V}$
Rise Time	$t_r$		2.1		ns	
Turn-Off Delay Time	$t_{d(off)}$		12.3		ns	
Fall Time	$t_f$		4.6		ns	
Gate Charge	$Q_g$		4.0		nC	$V_{DS}=30\text{V}, V_{GS}=5\text{V}, I_D=1.4\text{A}$
Total Gate Charge	$Q_g$		5.8		nC	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, I_D=1.4\text{A}$
Gate-Source Charge	$Q_{gs}$		1.4		nC	
Gate-Drain Charge	$Q_{gd}$		1.9		nC	
<b>SOURCE-DRAIN DIODE</b>						
Diode Forward Voltage (1)	$V_{SD}$		0.88	1.2	V	$T_J=25^{\circ}\text{C}, I_S=4\text{A}, V_{GS}=0\text{V}$
Reverse Recovery Time (3)	$t_{rr}$		19.2		ns	$T_J=25^{\circ}\text{C}, I_S=1.4\text{A}, di/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge (3)	$Q_{rr}$		30.3		nC	

## NOTES

- (1) Measured under pulsed conditions. Pulse width=300 $\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- (2) Switching characteristics are independent of operating junction temperature.
- (3) For design aid only, not subject to production testing.

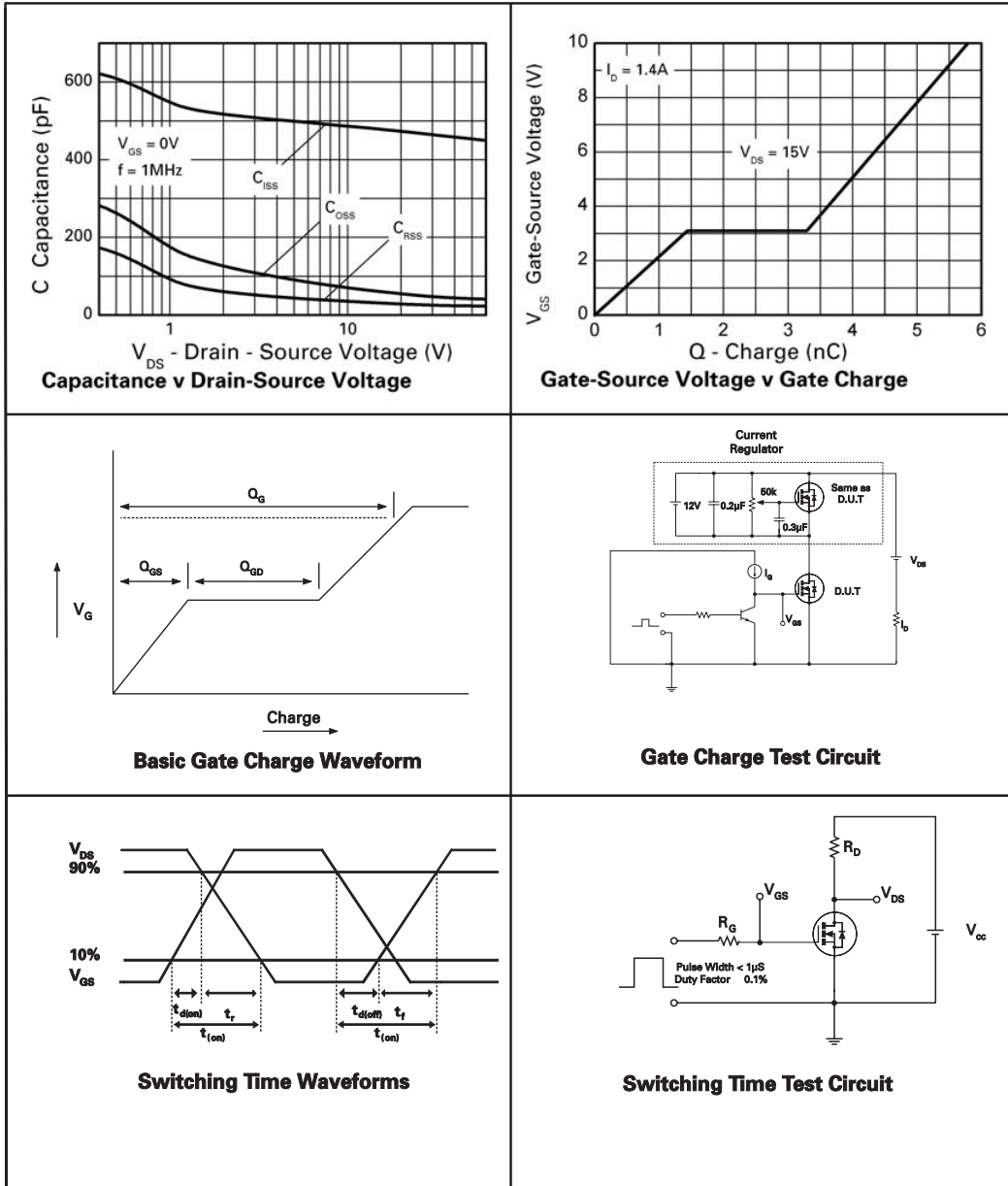
# ZXMN6A08E6

## TYPICAL CHARACTERISTICS



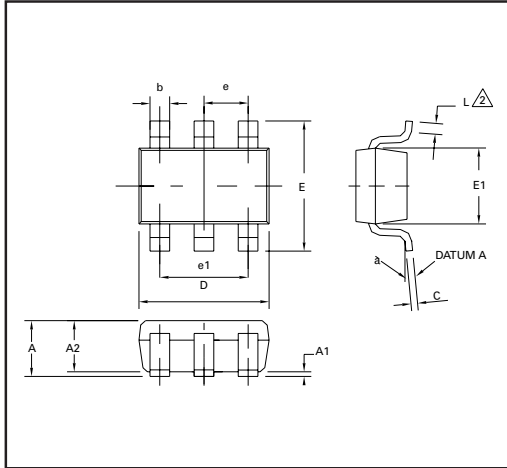
# ZXMN6A08E6

## TYPICAL CHARACTERISTICS

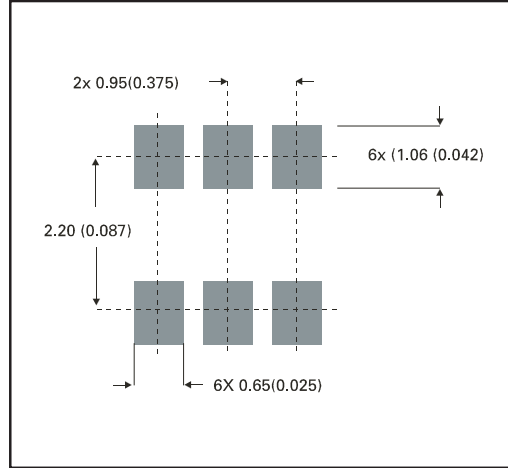


# ZXMN6A08E6

## PACKAGE OUTLINE



## PAD LAYOUT DETAILS



CONTROLLING DIMENSIONS IN MILLIMETERS APPROX CONVERSIONS INCHES.

## PACKAGE DIMENSIONS

DIM	Millimetres		Inches		DIM	Millimetres		Inches	
	Min	Max	Min	Max		Min	Max	Min	Max
A	0.90	1.45	0.35	0.057	E	2.60	3.00	0.102	0.118
A1	0.00	0.15	0	0.006	E1	1.50	1.75	0.059	0.069
A2	0.90	1.30	0.035	0.051	L	0.10	0.60	0.004	0.002
b	0.35	0.50	0.014	0.019	e	0.95 REF		0.037 REF	
C	0.09	0.20	0.0035	0.008	e1	1.90 REF		0.074 REF	
D	2.80	3.00	0.110	0.118	L	0°	10°	0°	10°

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